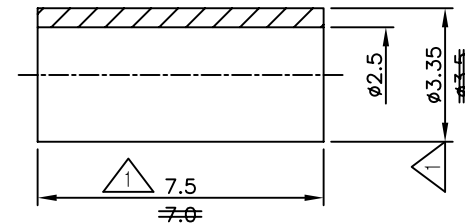
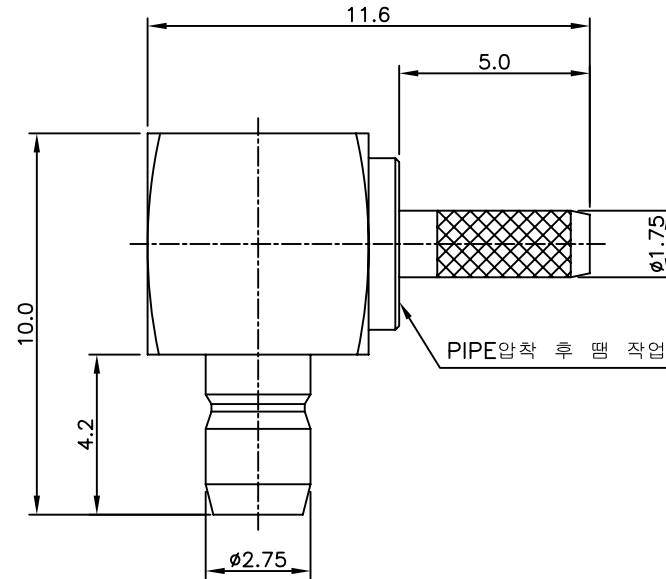
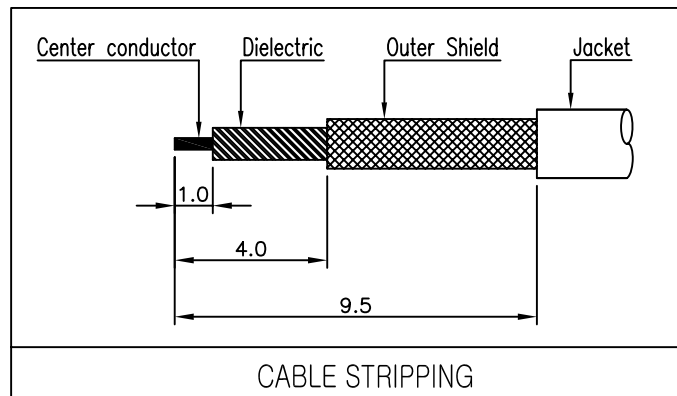


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2013.05.02.
1	[설번No.202201-0009] PIPE 압착 후 BURR 발생 개선으로 인한 PIPE 변경	S.Y.EUN	S.H.KIM	2022.01.18.



▶ CRIMPING 후 BODY+PIPE 뿔 작업 할 것.



5	COVER	1	MBsBD	Gold Plate	DCO00023-5/1
4	INSULATOR	1	MBsBD	Gold Plate	DIN02166-N/1
3	FERRULE	1	MBsBD	Nickel Plate Gold Plate	DFE00018-5/3 DFE00009-5/1
2	CONTACT	1	BeCu	Gold Plate	DCT02818-5/1
1-2	BODY (B)	1	MBsBD	Gold Plate	DBD03109-3/1
1-1	BODY (A)	1	MBsBD		DBB00339-5/1 DBD03309-3/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2022. 01. 18.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	S.H.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SSMB50 trans($\phi 2.75$) CABLE JL RG178
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	5/1	A4 DWG NO. CN02978-7/2 REVISION 1 SHEET 1 of 1
		UNIT	mm	